

### FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High surge capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU
- AEC-Q101 qualified and PPAP capable



AEC-Q101 Qualified

SMB(DO-214AA)

### MECHANICAL DATA

- Case: JEDEC SMB molded plastic body
- Terminals: Solder Plated, solderable per MIL-STD-750,method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Marking:SS1010B



Marking:

JF:Logo  
xxxx:Date code  
SS1010B-V:Type

### TYPICAL APPLICATIONS

For use in low voltage,high frequency inverter,DC/DC converters,  
free wheeling,and polarity protection applications

### MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise)

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum average forward rectified current	$I_{F(AV)}$	10.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	$I_{FSM}$	150	A
Operating junction temperature range	$T_j$	-55 to +150	°C
Storage temperature range	$T_{stg}$	-55 to +150	°C

## RATINGS AND CHARACTERISTICS OF SS1010B-V

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Test Conditions		Symbol	Typ.	Max.	Unit
Instaneous Forward Voltage	I <sub>F</sub> =10A	T <sub>J</sub> =25°C	V <sub>F</sub> <sup>1)</sup>	0.79	0.85	V
		T <sub>J</sub> =125°C		0.64	-	
	I <sub>F</sub> =5A	T <sub>J</sub> = 25°C		0.72	-	
		T <sub>J</sub> =125°C		0.57	-	
		Reverse Current		T <sub>J</sub> =25°C	V <sub>R</sub> =100V	
T <sub>J</sub> =125°C	-		5	mA		
Typical Junction Capacitance	4V ,1MHz		C <sub>J</sub>	237		pF

Notes: 1. Pulse test: 300 μs pulse width, 1% duty cycle

2. Pulse test: pulse width ≤ 40ms

### THERMAL CHARACTERISTICS

Parameter	Symbol	SMB	Unit
Typical thermal resistance <sup>3)</sup>	R <sub>θJA</sub>	70.0	°C/W
	R <sub>θJL</sub>	20.0	

3. Unit mounted on PC board with 5.0mm×5.0 mm (0.013 mm thick) copper pads as heat sink, (dP<sub>tot</sub>/dt<sub>j</sub>) < (1/R<sub>θJA</sub>) is thermal runaway condition for a diode

### AVAILABLE PACK INFORMATION

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Box Size L×W×H (mm)	Quantity (reel/box)	Carton Size L×W×H (mm)	Quantity (box/carton)	Quantity (K/carton)
SS1010B-V-SMB	T/R	Φ330	3000	330×333×39	2	370×370×360	8	48

# RATINGS AND CHARACTERISTICS OF SS1010B-V

Fig.1-Forward Current Derating Curve

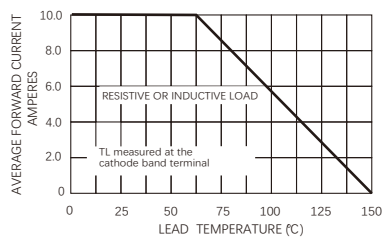


Fig.2-maximum Non-repetitive Peak Forward Surge Current

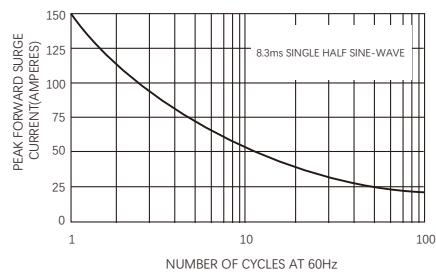


Fig.3-Typical Instantaneous Forward Characteristics

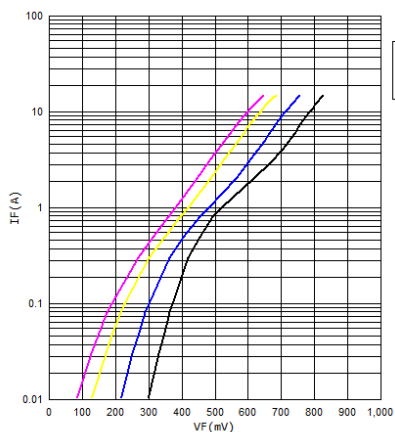


Fig.4-Typical Reverse Characteristics

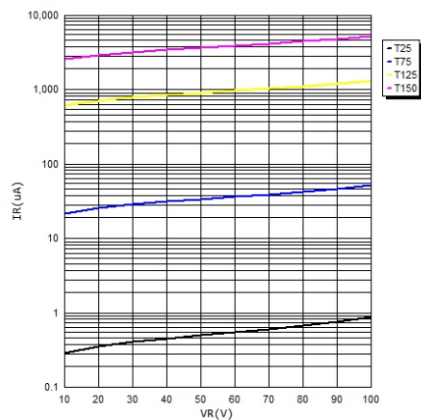
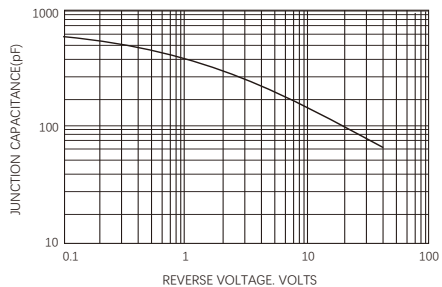
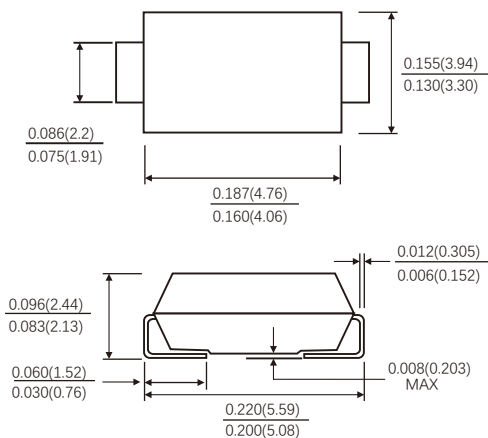


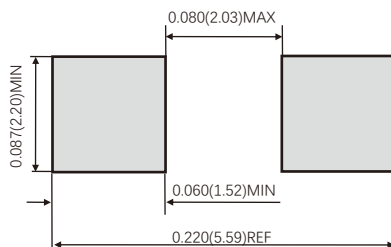
Fig.5-Typical Junction Capacitance



### SMB(DO-214AA)



### Suggested PAD Layout



Dimensions in inches and (millimeters)

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